

## IS62C64

### 8K x 8 LOW POWER CMOS STATIC RAM

MAY 1999

#### FEATURES

- CMOS low power operation
  - 400 mW (max.) operating
  - 25 mW (max.) standby
- Automatic power-down when chip is deselected
- TTL compatible interface levels
- Single 5V power supply
- Fully static operation: no clock or refresh required
- Three-state outputs
- Two Chip Enables ( $\overline{\text{CS1}}$  and CS2) for simple memory expansion
- Industrial temperature available

#### DESCRIPTION

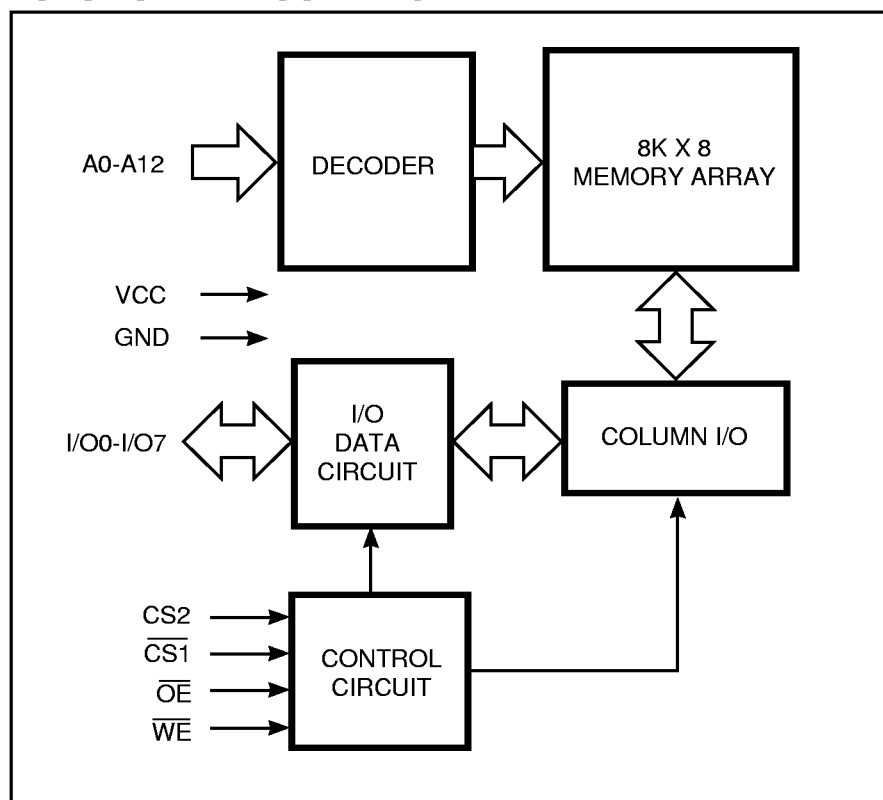
The *ISSI* IS62C64 is a low power, 8,192-word by 8-bit static RAM. It is fabricated using *ISSI*'s high-performance CMOS technology.

When  $\overline{\text{CS1}}$  is HIGH or CS2 is LOW (deselected), the device assumes a standby mode at which the power dissipation is reduced to 25  $\mu\text{W}$  (typical) with CMOS input levels.

Easy memory expansion is provided by using two Chip Select inputs,  $\overline{\text{CS1}}$  and CS2. The active LOW Write Enable ( $\overline{\text{WE}}$ ) controls both writing and reading of the memory.

The IS62C64 is packaged in the JEDEC standard 28-pin SOP surface mount packages.

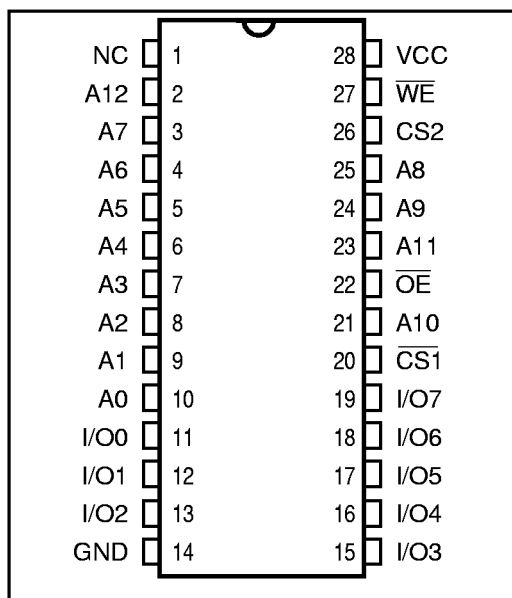
#### FUNCTIONAL BLOCK DIAGRAM



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## PIN CONFIGURATION

## 28-Pin SOP



## PIN DESCRIPTIONS

A0-A12	Address Inputs
$\overline{CS1}$	Chip Select 1 Input
CS2	Chip Select 2 Input
$\overline{OE}$	Output Enable Input
$\overline{WE}$	Write Enable Input
I/O0-I/O7	Input/Output
Vcc	Power
GND	Ground

## TRUTH TABLE

Mode	$\overline{WE}$	$\overline{CS1}$	CS2	$\overline{OE}$	I/O Operation	Vcc Current
Not Selected	X	H	X	X	High-Z	Isb1, Isb2
(Power-down)	X	X	L	X	High-Z	Isb1, Isb2
Output Disabled	H	L	H	H	High-Z	Icc1, Icc2
Read	H	L	H	L	DOUT	Icc1, Icc2
Write	L	L	H	X	DIN	Icc1, Icc2

ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Parameter	Value	Unit
V <sub>TERM</sub>	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
T <sub>BIAS</sub>	Temperature Under Bias	-55 to +125	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>T</sub>	Power Dissipation	1.0	W
I <sub>OUT</sub>	DC Output Current (LOW)	20	mA

## Note:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## OPERATING RANGE

Range	Ambient Temperature	Vcc
Commercial	0°C to +70°C	5V ± 10%
Industrial	-40°C to +85°C	5V ± 10%

**DC ELECTRICAL CHARACTERISTICS** (Over Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = −1.0 mA	2.4	—	V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 2.1 mA	—	0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub> + 0.5	V
V <sub>IL</sub>	Input LOW Voltage <sup>(1)</sup>		−0.5	0.8	V
I <sub>LI</sub>	Input Leakage	GND ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>	Com. Ind.	−2 10	μA
I <sub>LO</sub>	Output Leakage	GND ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub> , Outputs Disabled	Com. Ind.	−2 10	μA

**Notes:**

1. V<sub>IL</sub> = -3.0V for pulse width less than 10 ns.

**POWER SUPPLY CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

Symbol	Parameter	Test Conditions		-45 ns		-70 ns		Unit
				Min.	Max.	Min.	Max.	
I <sub>CC1</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA, f = 0	Com.	—	65	—	65	mA
			Ind.	—	75	—	75	
I <sub>CC2</sub>	V <sub>CC</sub> Dynamic Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub>	Com.	—	90	—	80	mA
			Ind.	—	100	—	90	
I <sub>SB1</sub>	TTL Standby Current (TTL Inputs)	V <sub>CC</sub> = Max., V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> CE1 ≥ V <sub>IH</sub> or CE2 ≤ V <sub>IL</sub> , f = 0	Com.	—	20	—	20	mA
			Ind.	—	30	—	30	
I <sub>SB2</sub>	CMOS Standby Current (CMOS Inputs)	V <sub>CC</sub> = Max., CE1 ≥ V <sub>CC</sub> - 0.2V, CE2 ≤ 0.2V, V <sub>IN</sub> ≥ V <sub>CC</sub> - 0.2V, or V <sub>IN</sub> ≤ 0.2V, f = 0	Com.	—	5	—	5	mA
			Ind.	—	10	—	10	

**Note:**

1. At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

**CAPACITANCE<sup>(1,2)</sup>**

Symbol	Parameter	Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	5	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>OUT</sub> = 0V	7	pF

**Notes:**

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T<sub>A</sub> = 25°C, f = 1 MHz, V<sub>CC</sub> = 5.0V.

**READ CYCLE SWITCHING CHARACTERISTICS<sup>(1)</sup>** (Over Commercial Operating Range)

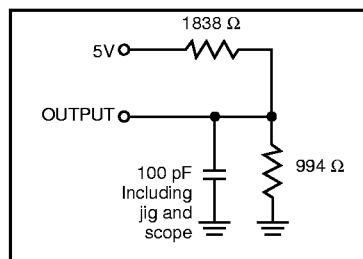
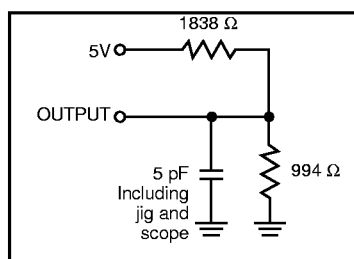
Symbol	Parameter	-45 ns		-70 ns		Unit
		Min.	Max.	Min.	Max.	
$t_{RC}$	Read Cycle Time	45	—	70	—	ns
$t_{AA}$	Address Access Time	—	45	—	70	ns
$t_{OHA}$	Output Hold Time	3	—	3	—	ns
$t_{ACS1}$	$\overline{CS1}$ Access Time	—	45	—	70	ns
$t_{ACS2}$	CS2 Access Time	—	45	—	70	ns
$t_{DOE}$	$\overline{OE}$ Access Time	—	25	—	35	ns
$t_{LZOE}^{(2)}$	$\overline{OS}$ to Low-Z Output	0	—	0	—	ns
$t_{HZOE}^{(2)}$	$\overline{OS}$ to High-Z Output	—	20	—	25	ns
$t_{LZCS1}^{(2)}$	$\overline{CS1}$ to Low-Z Output	3	—	3	—	ns
$t_{LZCS2}^{(2)}$	CS2 to Low-Z Output	3	—	3	—	ns
$t_{HZCS}^{(2)}$	$\overline{CS1}$ or CS2 to High-Z Output	—	20	—	25	ns
$t_{PU}^{(3)}$	$\overline{CS1}$ or CS2 to Power-Up	0	—	0	—	ns
$t_{PD}^{(3)}$	$\overline{CS1}$ or CS2 to Power-Down	—	30	—	50	ns

**Notes:**

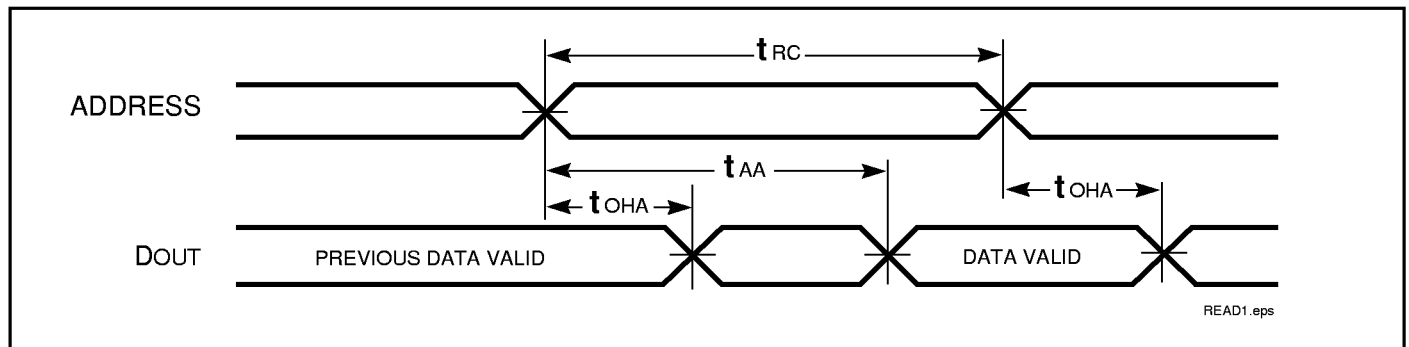
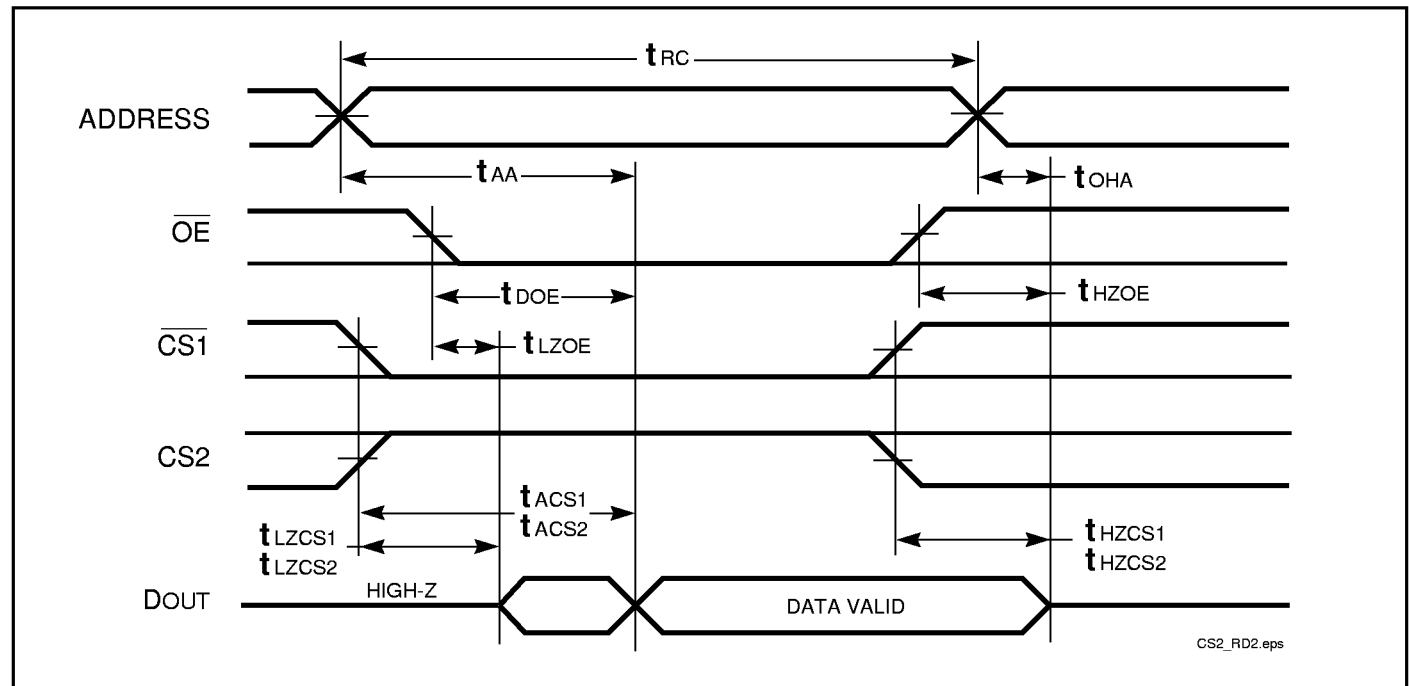
1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.
3. Not 100% tested.

**AC TEST CONDITIONS**

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	5 ns
Input and Output Timing and Reference Level	1.5V
Output Load	See Figures 1 and 2

**AC TEST LOADS****Figure 1.****Figure 2.**

## AC WAVEFORMS

READ CYCLE NO. 1<sup>(1,2)</sup>READ CYCLE NO. 2<sup>(1,3)</sup>

## Notes:

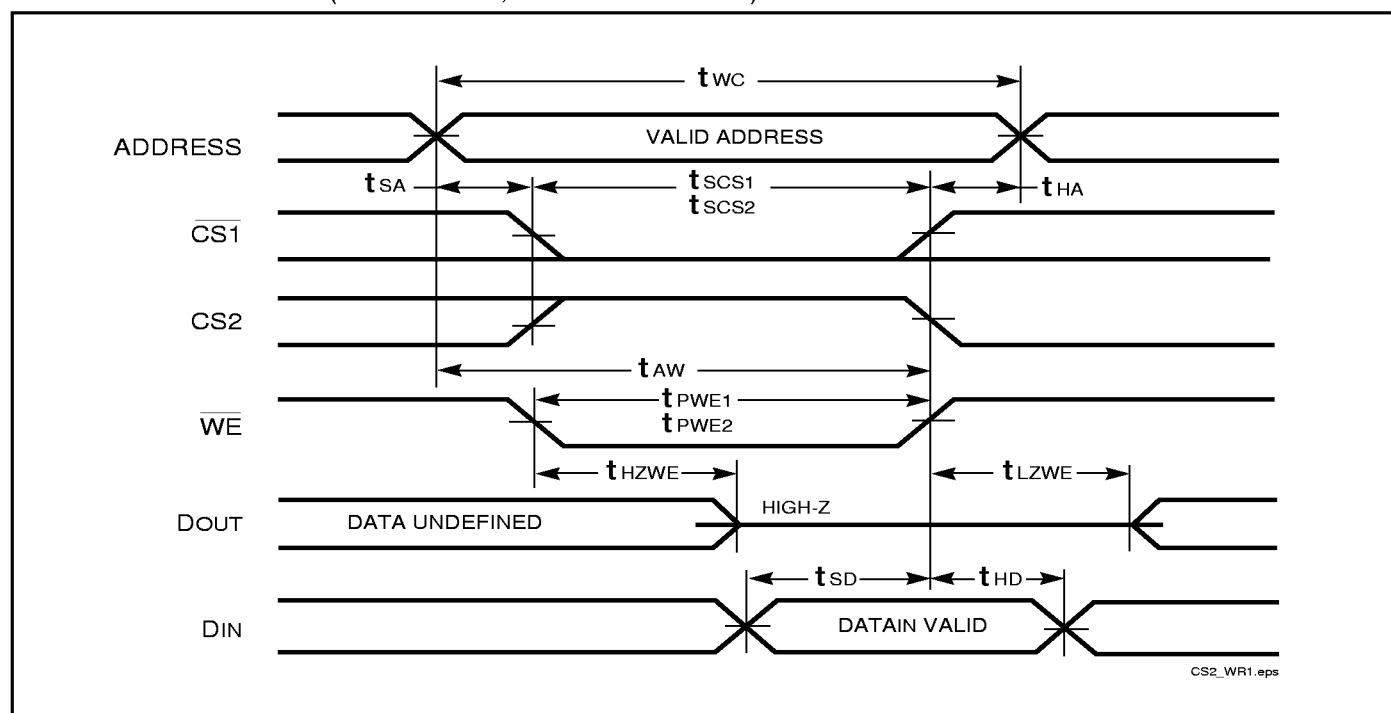
1.  $\overline{WE}$  is HIGH for a Read Cycle.
2. The device is continuously selected.  $\overline{OE}$ ,  $\overline{CS1} = V_{IL}$ ,  $CS2 = V_{IH}$ .
3. Address is valid prior to or coincident with  $\overline{CS1}$  LOW and CS2 HIGH transitions.

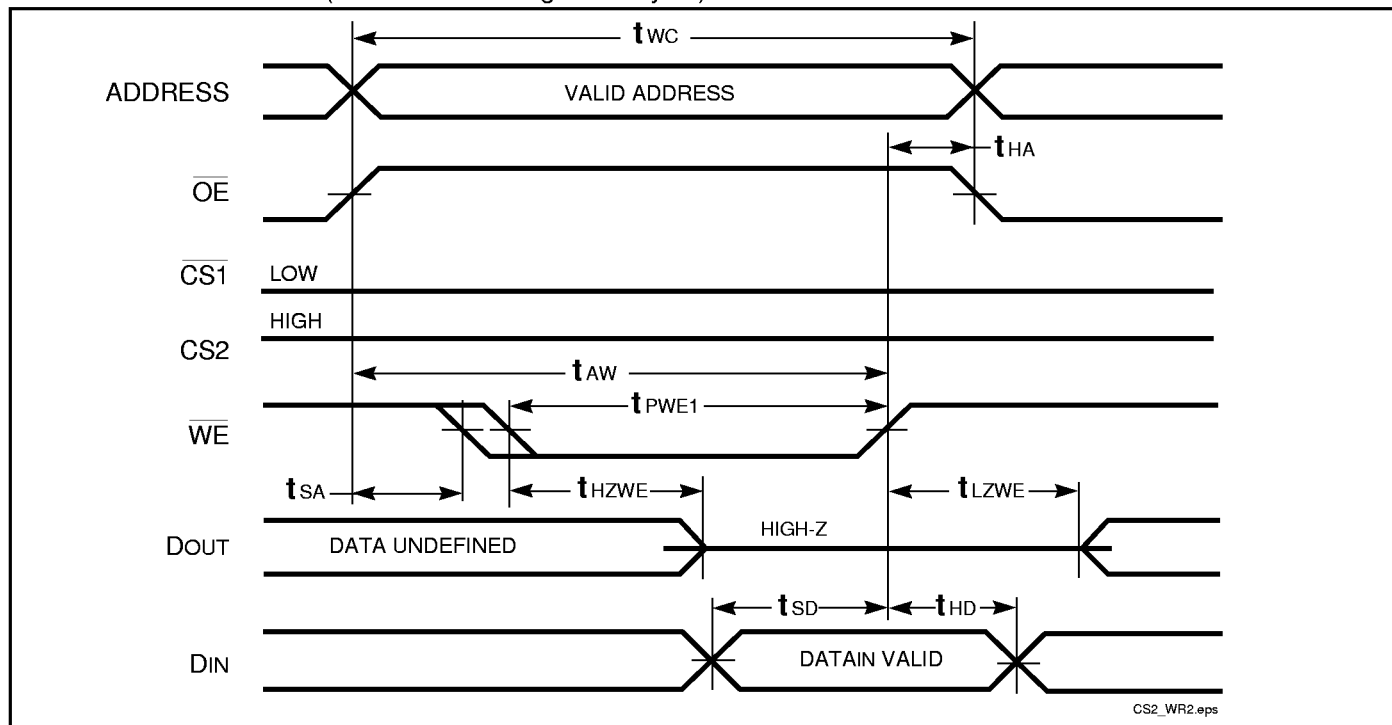
**WRITE CYCLE SWITCHING CHARACTERISTICS<sup>(1,3)</sup>** (Over Commercial Operating Range)

Symbol	Parameter	-45 ns		-70 ns		Unit
		Min.	Max.	Min.	Max.	
t <sub>WC</sub>	Write Cycle Time	45	—	70	—	ns
t <sub>SCS1</sub>	$\overline{CS1}$ to Write End	35	—	60	—	ns
t <sub>SCS2</sub>	CS2 to Write End	35	—	60	—	ns
t <sub>AW</sub>	Address Setup Time to Write End	35	—	60	—	ns
t <sub>HA</sub>	Address Hold from Write End	0	—	0	—	ns
t <sub>SA</sub>	Address Setup Time	0	—	0	—	ns
t <sub>PWE<sup>(4)</sup></sub>	$\overline{WE}$ Pulse Width	35	—	55	—	ns
t <sub>SD</sub>	Data Setup to Write End	25	—	30	—	ns
t <sub>HD</sub>	Data Hold from Write End	0	—	0	—	ns
t <sub>HZWE<sup>(2)</sup></sub>	$\overline{WE}$ LOW to High-Z Output	—	20	—	25	ns
t <sub>LZWE<sup>(2)</sup></sub>	$\overline{WE}$ HIGH to Low-Z Output	0	—	0	—	0 — ns

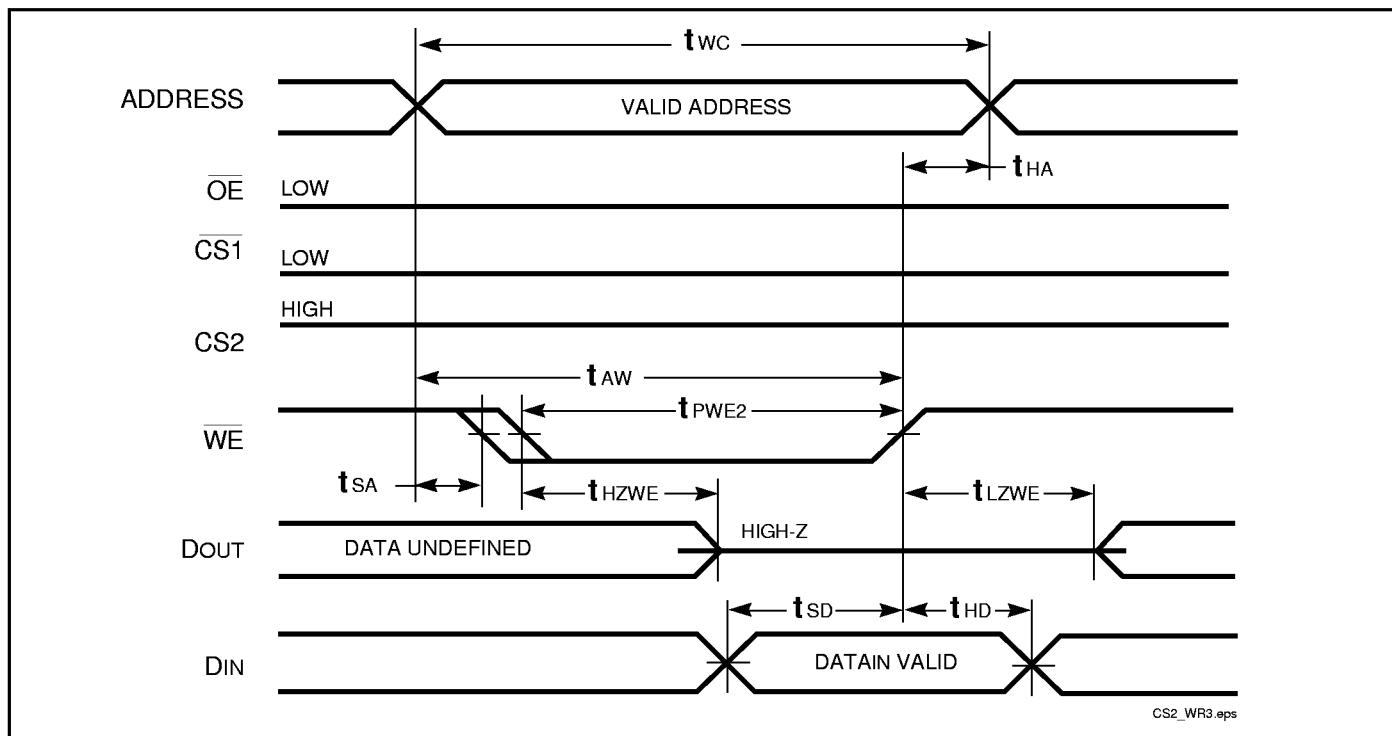
**Notes:**

1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of  $\overline{CS1}$  LOW, CS2 HIGH and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
4. Tested with  $\overline{OE}$  HIGH.

**AC WAVEFORMS****WRITE CYCLE NO. 1** ( $\overline{CS}$  Controlled,  $\overline{OE}$  is HIGH or LOW) <sup>(1)</sup>

**WRITE CYCLE NO. 2** ( $\overline{OE}$  is HIGH During Write Cycle) <sup>(1,2)</sup>**Notes:**

1. The internal write time is defined by the overlap of  $\overline{CS1}$  LOW,  $\overline{CS2}$  HIGH and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
2. I/O will assume the High-Z state if  $\overline{OE} = V_{IH}$ .

**WRITE CYCLE NO. 3** ( $\overline{OE}$  is LOW During Write Cycle)

**ORDERING INFORMATION****Commercial Range: 0°C to +70°C**

Speed (ns)	Order Part No.	Package
45	IS62C64-45U	330-mil Plastic SOP
70	IS62C64-70U	330-mil Plastic SOP

**ORDERING INFORMATION****Industrial Range: -40°C to +85°C**

Speed (ns)	Order Part No.	Package
45	IS62C64-45UI	330-mil Plastic SOP
70	IS62C64-70UI	330-mil Plastic SOP

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